CLAIMS

- 1. A process for producing and/or repairing very fine tips made from a photostructurable material on a carrier, in particular for utilization in scanning probe microscopy, characterized in that
 - the carrier is positioned on an exposure mask whose exposure section correlates to the tip to be produced or repaired,
 - the photostructurable material is applied onto the exposure mask and/or the carrier,
 - an exposure of the photostructurable material occurs via the exposure mask
 - in a manner known per se, the exposed photostructurable material is hardened and the unexposed material removed, and
 - the carrier with the tip and the exposure mask are separated from one another.

- 2. The process according to claim 1, characterized in that the exposure occurs in a directed manner, in particular in a direction diagonal or inclined towards the tip.
- 3. The process according to claim 2, characterized in that the exposure occurs at an angle of approximately 30° to a perpendicular line in relation to the exposure mask and/or to the surface of the carrier.
- 4. The process according to claim 1, characterized in that the tip to be produced or repaired is positioned on top of the exposure mask.
- 5. The process according to claim 1, characterized in that prior to the directing of the carrier a small amount of the photostructurable material is applied onto the exposure mask so that the carrier adheres to the latter.
- 6. The process according to claim 1, characterized in that a separation layer is provided for a facilitated separation of the carrier having the tip from the exposure mask.

- 7. The process according to claim 1, characterized in that preferably SU-8 is used as the photosensitive resist and that the so-called spin coating is used for its application.
- 8. The process according to claim 1, characterized in that the exposure mask is preferably made from quartz and the exposure section provides the tip with a radius of less than 1 μ m, preferably approximately 0.7 μ m.
- 9. The process according claim 1, characterized in that the shape and section of the exposure mask and/or the exposure angle are selected such that a tip develops having a predetermined radius and/or edge angle.
- 10. A process for producing and/or repairing very fine tips made from a photostructurable material on a carrier, in particular for utilization in scanning probe microscopy, comprising
 - providing a multitude of carriers positioned on a wafer in an undivided manner,

- arranging an exposure mask provided with a multitude of exposure sections positioned correspondingly,
- applying said photostructurable material onto said exposure mask and/or said carriers,
- conducting a simultaneous, inclined or diagonal exposure of all said provided carriers on said wafer via said exposure mask, hardening said exposed photostructurable material and removing any unexposed photostructurable material, and
- separating said exposure mask from the wafer.
- 11. A probe, particularly for use in scanning probe
 microscopy, characterized in that a tip made from a
 hardened photosensitive resist is produced and/or
 mounted laterally at or on a carrier preferably
 comprising a semiconductor or quartz material, in
 particular forming the cantilever of a scanning probe
 microscope.
- 12. The probe according to claim 11, characterized in that the tip is made and/or mounted from photosensitive

resist by means of a process known per se from the production of semiconductors, in particular subsequent to the production of the carrier.

- 13. Use of a tip produced according to claim 1 in a scanning probe microscope, in particular for the examination of so-called soft specimen and/or in a vacuum or at low pressure.
- 14. Use of a probe embodied according to claim 11 in a scanning probe microscope, in particular for the examination of so-called soft specimen and/or in a vacuum or at low pressure.